

"Other admission duties to follow"

thyssenkrupp AG / New loan issues and their warranties according to § 30e Para. 1, No. 2 of the WpHG [the German Securities Trading Act]

thyssenkrupp AG: Release according to Article 30e of the WpHG [the German Securities Trading Act] with the objective of Europe-wide distribution

Dissemination of a Admission duties to follow announcement transmitted by DGAP – a service of EQS Group AG. The issuer is solely responsible for the content of this announcement.

thyssenkrupp AG has issued the following bond:

ISIN: DE000A2AAPF1
Currency: Euro
Date of issue: March 8, 2016
Issue amount: 750,000,000 euros
Coupon: 2.75 %
Interest payment date: March 8, annual
Interest commencement date: March 8, 2016
First coupon payment date: March 8, 2017
Maturity: March 8, 2021

The bond issuance was documented under the company's 10 billion euro Debt Issuance Programme and is listed on the Luxembourg stock exchange.

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End of news